

PCN Number:	20170714000	PCN Date:	July 18, 2017
Title:	Datasheet for SN74AUP1G125		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN74AUP1G125

SCES595N – JULY 2004 – REVISED JULY 2017

Changes from Revision M (December 2015) to Revision N	Page
• Added DPW (X2SON) package.....	1
• Deleted <i>Device Comparison</i> table, see <i>Mechanical, Packaging, and Orderable Information</i> section at the end of the data sheet.....	1
• Changed <i>Simplified Schematic</i> with a new schematic.....	1
• Added column for X2SON (DPW) package and separated columns for DSBGA packages in <i>Pin Functions</i> table.....	3
• Changed values in the <i>Thermal Information</i> table to align with JEDEC standards.....	5
• Added <i>Balanced High-Drive CMOS Push-Pull Outputs, Standard CMOS Inputs, Clamp Diodes, Partial Power Down (I_{OPP}), and Over-voltage Tolerant Inputs</i>	15
• Added <i>Trace Example</i> and revised <i>Layout Guidelines</i>	18
• Added <i>Receiving Notification of Documentation Updates</i> section.....	20

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74AUP1G125	SCES595M	SCES595N

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/SN74AUP1G125>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

74AUP1G125DBVRG4	74AUP1G125DCKRG4	74AUP1G125DRLRG4	SN74AUP1G125DBVR
SN74AUP1G125DBVT	SN74AUP1G125DCKR	SN74AUP1G125DCKT	SN74AUP1G125DRLR
SN74AUP1G125DRYR	SN74AUP1G125DSFR	SN74AUP1G125YFPR	SN74AUP1G125YZPR
SN74AUP1G125YZTR			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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